


MATERIAL DECLARATION SHEET



Material Number	CD214L-T45CA~170CA			
Product Line	Semiconductor Products			
Compliance Date	2011/01/01			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt	Subpart mass of total wt. (%)
1	Dice	Silicon	7.358	Silicon	7440-21-3	60.1800%	1.816%	3.017%
				Phosphorus	7723-14-0	0.0100%	0.0003%	
				Boron	7440-42-8	0.0100%	0.0003%	
				Nickel	7440-02-0	14.8000%	0.447%	
				Lead	7439-92-1	12.5000%	0.377%	
				Silicon dioxide	7631-86-9	10.0000%	0.302%	
				Aluminum oxide	1344-28-1	2.5000%	0.0754%	
2	Die attach (Solder)	solder paste	13.250	Tin	7440-31-5	5.000%	0.272%	5.433%
				Lead	7439-92-1	92.500%	5.025%	
				Silver	7440-22-4	2.500%	0.136%	
3	Lead frame / Leads / Disc	N/A	110.667	Copper	7440-50-8	99.800%	45.286%	45.377%
				Iron	7439-89-6	0.150%	0.068%	
				Phosphorus	7723-14-0	0.050%	0.023%	
4	Molding Compound (Plastic Package Only)	Epoxy material	111.333	Silica	14808-60-7	76.000%	34.694%	45.650%
				Epoxy resin	25928-94-3	9.000%	4.109%	
				Phenolic resin-A,-B	9003-35-4	8.000%	3.652%	
				Hydroxide metal	N/A	6.000%	2.739%	
				Carbon black	1333-86-4	1.000%	0.457%	
5	Plating	Matte-Tin	1.275	Tin	7440-31-5	100.000%	0.523%	0.523%
				Total weight	243.883			

This Document was updated on: 2015/02/09

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements

7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

MATERIAL DECLARATION SHEET



7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound.